



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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SSTUB32866CHLFT

Category:	
Generic Part:	SSTUB32866C
Market Group:	RDIMM
Description:	1.8V REG. BUFFER (800 MHZ)



Parameters

Package	CABGA 96 (BFG96)
Speed	NA
Temperature	C
Voltage	3.3 V
Status	Active
Sample	No
Minimum Order Quantity	2500
Factory Order Increment	2500

Distributor Inventory

No Pricing information is available from our Distributors at this time.

Documents

Type	Title	Size	Revision Date
Product Change Notice	PCN# : A-0607-02 IDT Penang as Alternate Assembly Facility for ICS CVBGA and FPBGA	100 KB	07/27/2006
	PCN# A-0607-05 Green Mold Compound KMC3580 for BGA	195 KB	08/30/2006
	PCN# : A-0610-02 ASAT China as Alternate Facility for CABGA/CV BGA/FPBGA/TQFP/PQFP	253 KB	10/19/2006

Package

Description	CHIP ARRAY BGA 5.5 X 13.5 MM X 0.8 MM PI
Class	PLASTIC
Moisture Sensitivity Level (MSL)	3
Category	Green
Moisture Exposure Floor Life	168 hrs. @ <30°C/60%RH
Peak Reflow Temperature	260°C
Rebake Conditions	48 hrs.@125°C
Length	13.5
Mark	H
Width	5.5
Pitch	0.8
Thickness	1.4
Status	Active